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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	74
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LFBGA, CSPBGA
Supplier Device Package	100-CSBGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640e-5mn100c

Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

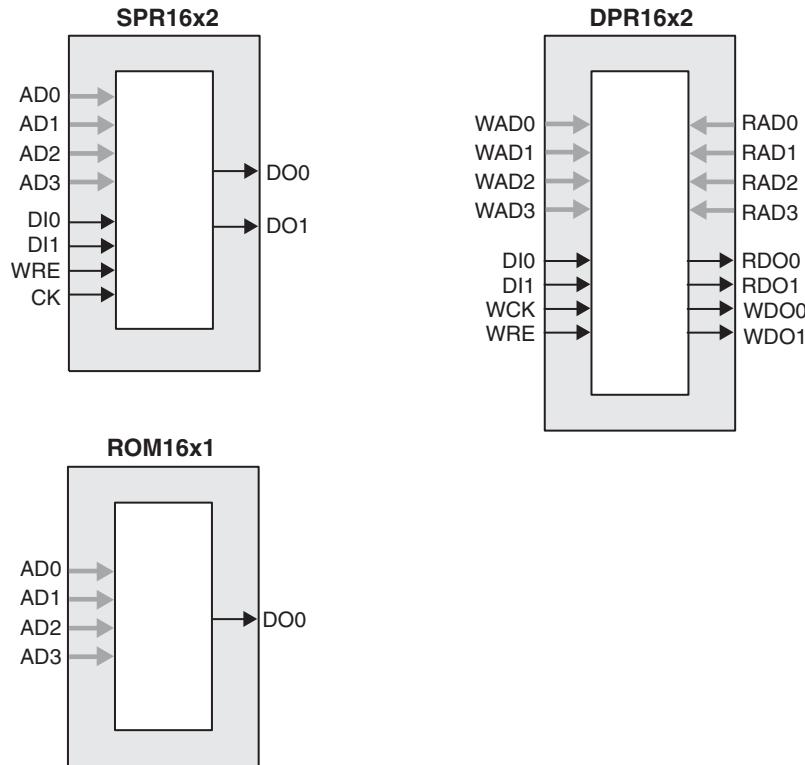
In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

Table 2-8. I/O Support Device by Device

	MachXO256	MachXO640	MachXO1200	MachXO2280
Number of I/O Banks	2	4	8	8
Type of Input Buffers	Single-ended (all I/O Banks)	Single-ended (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)
Types of Output Buffers	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)
Differential Output Emulation Capability	All I/O Banks	All I/O Banks	All I/O Banks	All I/O Banks
PCI Support	No	No	Top side only	Top side only

Table 2-9. Supported Input Standards

Input Standard	VCCIO (Typ.)				
	3.3V	2.5V	1.8V	1.5V	1.2V
Single Ended Interfaces					
LVTTL	Yes	Yes	Yes	Yes	Yes
LVCMOS33	Yes	Yes	Yes	Yes	Yes
LVCMOS25	Yes	Yes	Yes	Yes	Yes
LVCMOS18			Yes		
LVCMOS15				Yes	
LVCMOS12	Yes	Yes	Yes	Yes	Yes
PCI ¹	Yes				
Differential Interfaces					
BLVDS ² , LVDS ² , LVPECL ² , RSDS ²	Yes	Yes	Yes	Yes	Yes

1. Top Banks of MachXO1200 and MachXO2280 devices only.

2. MachXO1200 and MachXO2280 devices only.

Supply Current (Sleep Mode)^{1,2}

Symbol	Parameter	Device	Typ. ³	Max.	Units
I_{CC}	Core Power Supply	LCMxo256C	12	25	μA
		LCMxo640C	12	25	μA
		LCMxo1200C	12	25	μA
		LCMxo2280C	12	25	μA
I_{CCAUX}	Auxiliary Power Supply	LCMxo256C	1	15	μA
		LCMxo640C	1	25	μA
		LCMxo1200C	1	45	μA
		LCMxo2280C	1	85	μA
I_{CCIO}	Bank Power Supply ⁴	All LCMxo 'C' Devices	2	30	μA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.

2. Frequency = 0MHz.

3. $T_A = 25^\circ C$, power supplies at nominal voltage.

4. Per Bank.

Supply Current (Standby)^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
I_{CC}	Core Power Supply	LCMxo256C	7	mA
		LCMxo640C	9	mA
		LCMxo1200C	14	mA
		LCMxo2280C	20	mA
		LCMxo256E	4	mA
		LCMxo640E	6	mA
		LCMxo1200E	10	mA
		LCMxo2280E	12	mA
I_{CCAUX}	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LCMxo256E/C	5	mA
		LCMxo640E/C	7	mA
		LCMxo1200E/C	12	mA
		LCMxo2280E/C	13	mA
I_{CCIO}	Bank Power Supply ⁶	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND.

3. Frequency = 0MHz.

4. User pattern = blank.

5. $T_J = 25^\circ C$, power supplies at nominal voltage.

6. Per Bank. $V_{CCIO} = 2.5V$. Does not include pull-up/pull-down.

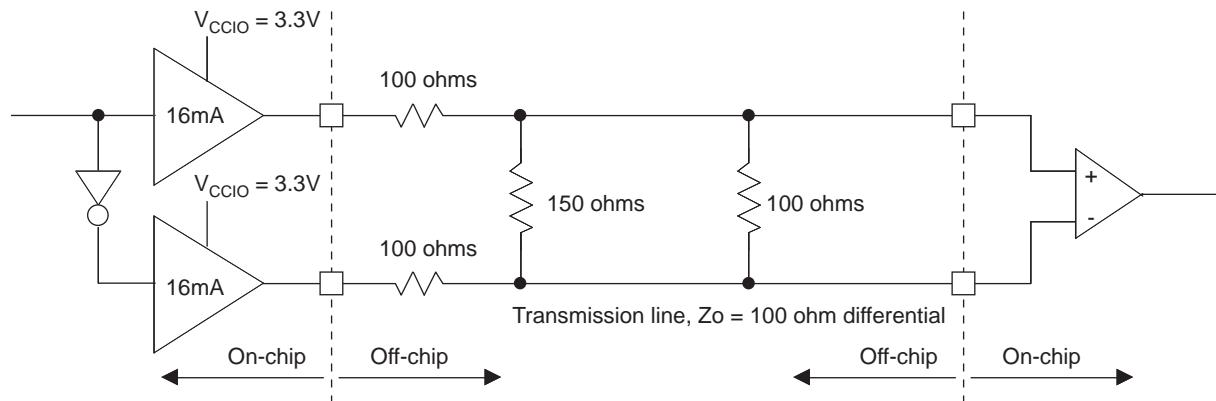
Table 3-2. BLVDS DC Conditions¹
Over Recommended Operating Conditions

Symbol	Description	Nominal		Units
		Zo = 45	Zo = 90	
Z _{OUT}	Output impedance	100	100	Ohms
R _{TLEFT}	Left end termination	45	90	Ohms
R _{TRIGHT}	Right end termination	45	90	Ohms
V _{OH}	Output high voltage	1.375	1.48	V
V _{OL}	Output low voltage	1.125	1.02	V
V _{OD}	Output differential voltage	0.25	0.46	V
V _{CM}	Output common mode voltage	1.25	1.25	V
I _{DC}	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

LVPECL

The MachXO family supports the differential LVPECL standard through emulation. This output standard is emulated using complementary LVCMS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The LVPECL input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

Table 3-3. LVPECL DC Conditions¹
Over Recommended Operating Conditions

Symbol	Description	Nominal	Units
Z _{OUT}	Output impedance	100	Ohms
R _P	Driver parallel resistor	150	Ohms
R _T	Receiver termination	100	Ohms
V _{OH}	Output high voltage	2.03	V
V _{OL}	Output low voltage	1.27	V
V _{OD}	Output differential voltage	0.76	V
V _{CM}	Output common mode voltage	1.65	V
Z _{BACK}	Back impedance	85.7	Ohms
I _{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

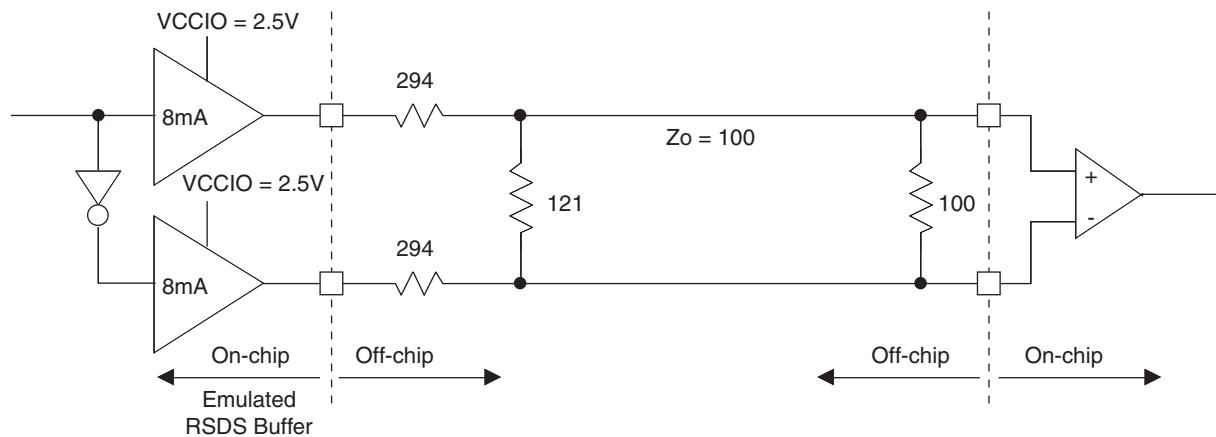


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	294	Ohms
R_P	Driver parallel resistor	121	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	Ohms
I_{DC}	DC output current	3.66	mA

MachXO External Switching Characteristics¹

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Global Clock without PLL)¹									
t _{PD}	Best Case t _{PD} Through 1 LUT	LCMxo256	—	3.5	—	4.2	—	4.9	ns
		LCMxo640	—	3.5	—	4.2	—	4.9	ns
		LCMxo1200	—	3.6	—	4.4	—	5.1	ns
		LCMxo2280	—	3.6	—	4.4	—	5.1	ns
t _{CO}	Best Case Clock to Output - From PFU	LCMxo256	—	4.0	—	4.8	—	5.6	ns
		LCMxo640	—	4.0	—	4.8	—	5.7	ns
		LCMxo1200	—	4.3	—	5.2	—	6.1	ns
		LCMxo2280	—	4.3	—	5.2	—	6.1	ns
t _{SU}	Clock to Data Setup - To PFU	LCMxo256	1.3	—	1.6	—	1.8	—	ns
		LCMxo640	1.1	—	1.3	—	1.5	—	ns
		LCMxo1200	1.1	—	1.3	—	1.6	—	ns
		LCMxo2280	1.1	—	1.3	—	1.5	—	ns
t _H	Clock to Data Hold - To PFU	LCMxo256	-0.3	—	-0.3	—	-0.3	—	ns
		LCMxo640	-0.1	—	-0.1	—	-0.1	—	ns
		LCMxo1200	0.0	—	0.0	—	0.0	—	ns
		LCMxo2280	-0.4	—	-0.4	—	-0.4	—	ns
f _{MAX_IO}	Clock Frequency of I/O and PFU Register	LCMxo256	—	600	—	550	—	500	MHz
		LCMxo640	—	600	—	550	—	500	MHz
		LCMxo1200	—	600	—	550	—	500	MHz
		LCMxo2280	—	600	—	550	—	500	MHz
t _{SKEW_PRI}	Global Clock Skew Across Device	LCMxo256	—	200	—	220	—	240	ps
		LCMxo640	—	200	—	220	—	240	ps
		LCMxo1200	—	220	—	240	—	260	ps
		LCMxo2280	—	220	—	240	—	260	ps

1. General timing numbers based on LVCMS2.5V, 12 mA.

Rev. A 0.19

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	420	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 ^{5, 6}	18	25	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	420	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	210	MHz
f_{VCO}	PLL VCO Frequency		420	840	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 ^{5, 6}	18	25	MHz
AC Characteristics					
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected ³	45	55	%
t_{PH}^4	Output Phase Accuracy		—	0.05	UI
t_{OPJIT}^1	Output Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	+/-120	ps
		$f_{OUT} < 100$ MHz	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	+/-200	ps
t_W	Output Clock Pulse Width	At 90% or 10% ³	1	—	ns
t_{LOCK}^2	PLL Lock-in Time		—	150	μs
t_{PA}	Programmable Delay Unit		100	450	ps
t_{IPJIT}	Input Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	+/-200	ps
		$f_{OUT} < 100$ MHz	—	0.02	UI
t_{FBKDLY}	External Feedback Delay		—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	ns
t_{RST}	RST Pulse Width		10	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock.

2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.

3. Using LVDS output buffers.

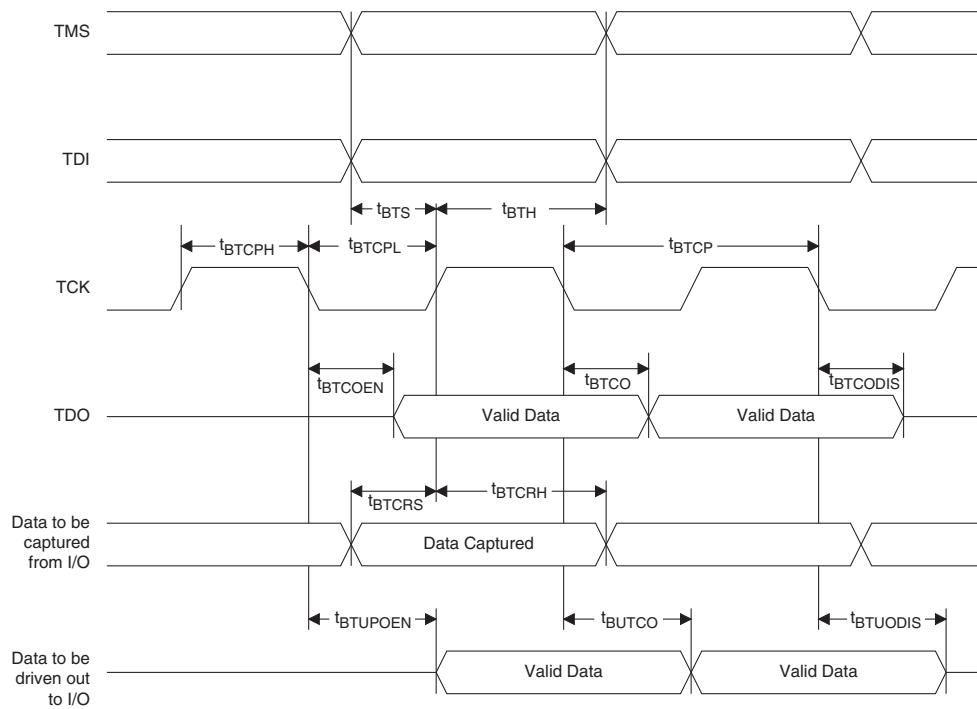
4. CLKOS as compared to CLKOP output.

5. When using an input frequency less than 25 MHz the output frequency must be less than or equal to 4 times the input frequency.

6. The on-chip oscillator can be used to provide reference clock input to the PLL provided the output frequency restriction for clock inputs below 25 MHz are followed.

Rev. A 0.19

Figure 3-5. JTAG Port Timing Waveforms



Switching Test Conditions

Figure 3-6 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-6. Output Test Load, LVTTL and LVCMOS Standards

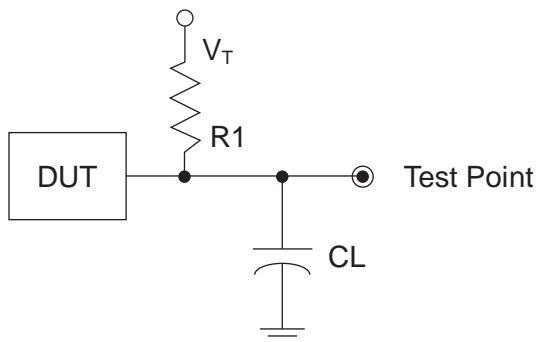


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R ₁	C _L	Timing Ref.	V _T
LVTTL and LVCMOS settings (L -> H, H -> L)	∞	0pF	LVTTL, LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = V _{CCIO} /2	—
			LVCMOS 1.8 = V _{CCIO} /2	—
			LVCMOS 1.5 = V _{CCIO} /2	—
			LVCMOS 1.2 = V _{CCIO} /2	—
LVTTL and LVCMOS 3.3 (Z -> H)	188	0pF	1.5	V _{OL}
LVTTL and LVCMOS 3.3 (Z -> L)				V _{OH}
Other LVCMOS (Z -> H)			V _{CCIO} /2	V _{OL}
Other LVCMOS (Z -> L)			V _{CCIO} /2	V _{OH}
LVTTL + LVCMOS (H -> Z)			V _{OH} - 0.15	V _{OL}
LVTTL + LVCMOS (L -> Z)			V _{OL} - 0.15	V _{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number]_[A/B/C/D/E/F]	I/O	<p>[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top).</p> <p>[Row/Column Number] indicates the PFU row or the column of the device on which the PIO Group exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number.</p> <p>[A/B/C/D/E/F] indicates the PIO within the group to which the pad is connected.</p> <p>Some of these user programmable pins are shared with special function pins. When not used as special function pins, these pins can be programmed as I/Os for user logic.</p> <p>During configuration of the user-programmable I/Os, the user has an option to tri-state the I/Os and enable an internal pull-up resistor. This option also applies to unused pins (or those not bonded to a package pin). The default during configuration is for user-programmable I/Os to be tri-stated with an internal pull-up resistor enabled. When the device is erased, I/Os will be tri-stated with an internal pull-up resistor enabled.</p>
GSRN	I	Global RESET signal (active low). Dedicated pad, when not in use it can be used as an I/O pin.
TSALL	I	TSALL is a dedicated pad for the global output enable signal. When TSALL is high all the outputs are tristated. It is a dual function pin. When not in use, it can be used as an I/O pin.
NC	—	No connect.
GND	—	GND - Ground. Dedicated pins.
V _{CC}	—	VCC - The power supply pins for core logic. Dedicated pins.
V _{CCAUX}	—	VCCAUX - the Auxiliary power supply pin. This pin powers up a variety of internal circuits including all the differential and referenced input buffers. Dedicated pins.
V _{CCIOx}	—	V _{CCIO} - The power supply pins for I/O Bank x. Dedicated pins.
SLEEPN ¹	I	Sleep Mode pin - Active low sleep pin. ^b When this pin is held high, the device operates normally. ^b This pin has a weak internal pull-up, but when unused, an external pull-up to V _{CC} is recommended. When driven low, the device moves into Sleep mode after a specified time.
PLL and Clock Functions (Used as user programmable I/O pins when not used for PLL or clock pins)		
[LOC][0]_PLL[T, C]_IN	—	Reference clock (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
[LOC][0]_PLL[T, C]_FB	—	Optional feedback (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
PCLK [n]_[1:0]	—	Primary Clock Pads, n per side.
Test and Programming (Dedicated pins)		
TMS	I	Test Mode Select input pin, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data input pin, used to load data into the device using an 1149.1 state machine.
TDO	O	Output pin -Test Data output pin used to shift data out of the device using 1149.1.

¹. Applies to MachXO "C" devices only. NC for "E" devices.

Power Supply and NC (Cont.)

Signal	132 csBGA ¹	256 caBGA / 256 ftBGA ¹	324 ftBGA ¹
VCC	H3, P6, G12, C7	G7, G10, K7, K10	F14, G11, G9, H7, L7, M9
VCCIO0	LCMxo640: B11, C5 LCMxo1200/2280: C5	LCMxo640: F8, F7, F9, F10 LCMxo1200/2280: F8, F7	G8, G7
VCCIO1	LCMxo640: L12, E12 LCMxo1200/2280: B11	LCMxo640: H11, G11, K11, J11 LCMxo1200/2280: F9, F10	G12, G10
VCCIO2	LCMxo640: N2, M10 LCMxo1200/2280: E12	LCMxo640: L9, L10, L8, L7 LCMxo1200/2280: H11, G11	J12, H12
VCCIO3	LCMxo640: D2, K3 LCMxo1200/2280: L12	LCMxo640: K6, J6, H6, G6 LCMxo1200/2280: K11, J11	L12, K12
VCCIO4	LCMxo640: None LCMxo1200/2280: M10	LCMxo640: None LCMxo1200/2280: L9, L10	M12, M11
VCCIO5	LCMxo640: None LCMxo1200/2280: N2	LCMxo640: None LCMxo1200/2280: L8, L7	M8, R9
VCCIO6	LCMxo640: None LCMxo1200/2280: K3	LCMxo640: None LCMxo1200/2280: K6, J6	M7, K7
VCCIO7	LCMxo640: None LCMxo1200/2280: D2	LCMxo640: None LCMxo1200/2280: H6, G6	H6, J7
VCCAUX	P7, A7	T9, A8	M10, F9
GND ²	F1, P9, J14, C9, A10, B4, L13, D13, P2, N11, E1, L2	A1, A16, F11, G8, G9, H7, H8, H9, H10, J7, J8, J9, J10, K8, K9, L6, T1, T16	E14, F16, H10, H11, H8, H9, J10, J11, J4, J8, J9, K10, K11, K17, K8, K9, L10, L11, L8, L9, N2, P14, P5, R7
NC ³	—	LCMxo640: E4, E5, F5, F6, C3, C2, G4, G5, H4, H5, K5, K4, M5, M4, P2, P3, N5, N6, M7, M8, N10, N11, R15, R16, P15, P16, M11, L11, N12, N13, M13, M12, K12, J12, F12, F13, E12, E13, D13, D14, B15, A15, C14, B14, E11, E10, E7, E6, D4, D3, B3, B2 LCMxo1200: None LCMxo2280: None	—

1. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
2. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
3. NC pins should not be connected to any active signals, VCC or GND.

LCMxo256 and LCMxo640 Logic Signal Connections: 100 TQFP

Pin Number	LCMxo256				LCMxo640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	1		T	PL2A	3		T
2	PL2B	1		C	PL2C	3		T
3	PL3A	1		T	PL2B	3		C
4	PL3B	1		C	PL2D	3		C
5	PL3C	1		T	PL3A	3		T
6	PL3D	1		C	PL3B	3		C
7	PL4A	1		T	PL3C	3		T
8	PL4B	1		C	PL3D	3		C
9	PL5A	1		T	PL4A	3		
10	VCCIO1	1			VCCIO3	3		
11	PL5B	1		C	PL4C	3		T
12	GNDIO1	1			GNDIO3	3		
13	PL5C	1		T	PL4D	3		C
14	PL5D	1	GSRN	C	PL5B	3	GSRN	
15	PL6A	1		T	PL7B	3		
16	PL6B	1	TSALL	C	PL8C	3	TSALL	T
17	PL7A	1		T	PL8D	3		C
18	PL7B	1		C	PL9A	3		
19	PL7C	1		T	PL9C	3		
20	PL7D	1		C	PL10A	3		
21	PL8A	1		T	PL10C	3		
22	PL8B	1		C	PL11A	3		
23	PL9A	1		T	PL11C	3		
24	VCCIO1	1			VCCIO3	3		
25	GNDIO1	1			GNDIO3	3		
26	TMS	1	TMS		TMS	2	TMS	
27	PL9B	1		C	PB2C	2		
28	TCK	1	TCK		TCK	2	TCK	
29	PB2A	1		T	VCCIO2	2		
30	PB2B	1		C	GNDIO2	2		
31	TDO	1	TDO		TDO	2	TDO	
32	PB2C	1		T	PB4C	2		
33	TDI	1	TDI		TDI	2	TDI	
34	PB2D	1		C	PB4E	2		
35	VCC	-			VCC	-		
36	PB3A	1	PCLK1_1**	T	PB5B	2	PCLK2_1**	
37	PB3B	1		C	PB5D	2		
38	PB3C	1	PCLK1_0**	T	PB6B	2	PCLK2_0**	
39	PB3D	1		C	PB6C	2		
40	GND	-			GND	-		
41	VCCIO1	1			VCCIO2	2		
42	GNDIO1	1			GNDIO2	2		

LCMxo256 and LCMxo640 Logic Signal Connections: 100 csBGA (Cont.)

LCMxo256					LCMxo640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
P13	PB5A	1			P13	PB9C	2		T
M12*	SLEEPN	-	SLEEPN		M12*	SLEEPN	-	SLEEPN	
P14	PB5C	1		T	P14	PB9D	2		C
N13	PB5D	1		C	N13	PB9F	2		
N14	PR9B	0		C	N14	PR11D	1		C
M14	PR9A	0		T	M14	PR11B	1		C
L13	PR8B	0		C	L13	PR11C	1		T
L14	PR8A	0		T	L14	PR11A	1		T
M13	PR7D	0		C	M13	PR10D	1		C
K14	PR7C	0		T	K14	PR10C	1		T
K13	PR7B	0		C	K13	PR10B	1		C
J14	PR7A	0		T	J14	PR10A	1		T
J13	PR6B	0		C	J13	PR9D	1		
H13	PR6A	0		T	H13	PR9B	1		
G14	GNDIO0	0			G14	GNDIO1	1		
G13	PR5D	0		C	G13	PR7B	1		
F14	PR5C	0		T	F14	PR6C	1		
F13	PR5B	0		C	F13	PR6B	1		
E14	PR5A	0		T	E14	PR5D	1		
E13	PR4B	0		C	E13	PR5B	1		
D14	PR4A	0		T	D14	PR4D	1		
D13	PR3D	0		C	D13	PR4B	1		
C14	PR3C	0		T	C14	PR3D	1		
C13	PR3B	0		C	C13	PR3B	1		
B14	PR3A	0		T	B14	PR2D	1		
C12	PR2B	0		C	C12	PR2B	1		
B13	GNDIO0	0			B13	GNDIO1	1		
A13	PR2A	0		T	A13	PT9F	0		C
A12	PT5C	0			A12	PT9E	0		T
B11	PT5B	0		C	B11	PT9C	0		
A11	PT5A	0		T	A11	PT9A	0		
B12	PT4F	0		C	B12	VCCIO0	0		
A10	PT4E	0		T	A10	GNDIO0	0		
B10	PT4D	0		C	B10	PT7E	0		
A9	PT4C	0		T	A9	PT7A	0		
A8	PT4B	0	PCLK0_1**	C	A8	PT6B	0	PCLK0_1**	
B8	PT4A	0	PCLK0_0**	T	B8	PT5B	0	PCLK0_0**	C
A7	PT3D	0		C	A7	PT5A	0		T
B7	VCCAUX	-			B7	VCCAUX	-		
A6	PT3C	0		T	A6	PT4F	0		
B6	VCC	-			B6	VCC	-		
A5	PT3B	0		C	A5	PT3F	0		

**LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections:
 132 csBGA (Cont.)**

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B9	PT7B	0		C	B9	PT9B	1		C	B9	PT12D	1		C
A9	PT7A	0		T	A9	PT9A	1		T	A9	PT12C	1		T
A8	PT6B	0	PCLK0_1***	C	A8	PT7D	1	PCLK1_1***		A8	PT10B	1	PCLK1_1***	
B8	PT6A	0		T	B8	PT7B	1			B8	PT9D	1		
C8	PT5B	0	PCLK0_0***	C	C8	PT6F	0	PCLK1_0***		C8	PT9B	1	PCLK1_0***	
B7	PT5A	0		T	B7	PT6D	0			B7	PT8D	0		
A7	VCCAUX	-			A7	VCCAUX	-			A7	VCCAUX	-		
C7	VCC	-			C7	VCC	-			C7	VCC	-		
A6	PT4D	0		C	A6	PT5D	0		C	A6	PT7B	0		C
B6	PT4C	0		T	B6	PT5C	0		T	B6	PT7A	0		T
C6	PT3F	0		C	C6	PT5B	0		C	C6	PT6D	0		
B5	PT3E	0		T	B5	PT5A	0		T	B5	PT6E	0		T
A5	PT3D	0			A5	PT4B	0			A5	PT6F	0		C
B4	GNDIO0	0			B4	GNDIO0	0			B4	GNDIO0	0		
A4	PT3B	0			A4	PT3D	0		C	A4	PT4B	0		C
C4	PT2F	0			C4	PT3C	0		T	C4	PT4A	0		T
A3	PT2D	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2C	0		T	A2	PT2B	0		C	A2	PT2B	0		C
B3	PT2B	0		C	B3	PT3A	0		T	B3	PT3A	0		T
A1	PT2A	0		T	A1	PT2A	0		T	A1	PT2A	0		T
F1	GND	-			F1	GND	-			F1	GND	-		
P9	GND	-			P9	GND	-			P9	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
C9	GND	-			C9	GND	-			C9	GND	-		
C5	VCCIO0	0			C5	VCCIO0	0			C5	VCCIO0	0		
B11	VCCIO0	0			B11	VCCIO1	1			B11	VCCIO1	1		
E12	VCCIO1	1			E12	VCCIO2	2			E12	VCCIO2	2		
L12	VCCIO1	1			L12	VCCIO3	3			L12	VCCIO3	3		
M10	VCCIO2	2			M10	VCCIO4	4			M10	VCCIO4	4		
N2	VCCIO2	2			N2	VCCIO5	5			N2	VCCIO5	5		
D2	VCCIO3	3			D2	VCCIO7	7			D2	VCCIO7	7		
K3	VCCIO3	3			K3	VCCIO6	6			K3	VCCIO6	6		

*Supports true LVDS outputs.

**NC for "E" devices.

***Primary clock inputs are single-ended.

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
 256 caBGA / 256 ftBGA**

LCMxo640					LCMxo1200					LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3			GND	GNDIO7	7			GND	GNDIO7	7		
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
E4	NC				E4	PL2A	7		T	E4	PL2A	7	LUM0_PLLT_FB_A	T
E5	NC				E5	PL2B	7		C	E5	PL2B	7	LUM0_PLLC_FB_A	C
F5	NC				F5	PL3A	7		T*	F5	PL3A	7		T*
F6	NC				F6	PL3B	7		C*	F6	PL3B	7		C*
F3	PL3A	3		T	F3	PL3C	7		T	F3	PL3C	7	LUM0_PLLT_IN_A	T
F4	PL3B	3		C	F4	PL3D	7		C	F4	PL3D	7	LUM0_PLLC_IN_A	C
E3	PL2C	3		T	E3	PL4A	7		T*	E3	PL4A	7		T*
E2	PL2D	3		C	E2	PL4B	7		C*	E2	PL4B	7		C*
C3	NC				C3	PL4C	7		T	C3	PL4C	7		T
C2	NC				C2	PL4D	7		C	C2	PL4D	7		C
B1	PL2A	3		T	B1	PL5A	7		T*	B1	PL5A	7		T*
C1	PL2B	3		C	C1	PL5B	7		C*	C1	PL5B	7		C*
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
GND	GNDIO3	3			GND	GNDIO7	7			GND	GNDIO7	7		
D2	PL3C	3		T	D2	PL5C	7		T	D2	PL6C	7		T
D1	PL3D	3		C	D1	PL5D	7		C	D1	PL6D	7		C
F2	PL5A	3		T	F2	PL6A	7		T*	F2	PL7A	7		T*
G2	PL5B	3	GSRN	C	G2	PL6B	7	GSRN	C*	G2	PL7B	7	GSRN	C*
E1	PL4A	3		T	E1	PL6C	7		T	E1	PL7C	7		T
F1	PL4B	3		C	F1	PL6D	7		C	F1	PL7D	7		C
G4	NC				G4	PL7A	7		T*	G4	PL8A	7		T*
G5	NC				G5	PL7B	7		C*	G5	PL8B	7		C*
GND	GND	-			GND	GND	-			GND	GND	-		
G3	PL4C	3		T	G3	PL7C	7		T	G3	PL8C	7		T
H3	PL4D	3		C	H3	PL7D	7		C	H3	PL8D	7		C
H4	NC				H4	PL8A	7		T*	H4	PL9A	7		T*
H5	NC				H5	PL8B	7		C*	H5	PL9B	7		C*
-	-				VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
-	-				GND	GNDIO7	7			GND	GNDIO7	7		
G1	PL5C	3		T	G1	PL8C	7		T	G1	PL10C	7		T
H1	PL5D	3		C	H1	PL8D	7		C	H1	PL10D	7		C
H2	PL6A	3		T	H2	PL9A	6		T*	H2	PL11A	6		T*
J2	PL6B	3		C	J2	PL9B	6		C*	J2	PL11B	6		C*
J3	PL7C	3		T	J3	PL9C	6		T	J3	PL11C	6		T
K3	PL7D	3		C	K3	PL9D	6		C	K3	PL11D	6		C
J1	PL6C	3		T	J1	PL10A	6		T*	J1	PL12A	6		T*
-	-				VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
-	-				GND	GNDIO6	6			GND	GNDIO6	6		
K1	PL6D	3		C	K1	PL10B	6		C*	K1	PL12B	6		C*
K2	PL9A	3		T	K2	PL10C	6		T	K2	PL12C	6		T
L2	PL9B	3		C	L2	PL10D	6		C	L2	PL12D	6		C
L1	PL7A	3		T	L1	PL11A	6		T*	L1	PL13A	6		T*
M1	PL7B	3		C	M1	PL11B	6		C*	M1	PL13B	6		C*
P1	PL8D	3		C	P1	PL11D	6		C	P1	PL14D	6		C
N1	PL8C	3	TSALL	T	N1	PL11C	6	TSALL	T	N1	PL14C	6	TSALL	T
L3	PL10A	3		T	L3	PL12A	6		T*	L3	PL15A	6		T*
M3	PL10B	3		C	M3	PL12B	6		C*	M3	PL15B	6		C*
M2	PL9C	3		T	M2	PL12C	6		T	M2	PL15C	6		T
N2	PL9D	3		C	N2	PL12D	6		C	N2	PL15D	6		C
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		

LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
V10	PB9B	4		C
N10	PB9C	4		T
R10	PB9D	4		C
P10	PB10F	4	PCLK4_1***	C
T10	PB10E	4		T
U10	PB10D	4		C
V11	PB10C	4		T
U11	PB10B	4	PCLK4_0***	C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
T11	PB10A	4		T
U12	PB11A	4		T
R11	PB11B	4		C
GND	GND	-		
T12	PB11C	4		T
P11	PB11D	4		C
V12	PB12A	4		T
V13	PB12B	4		C
R12	PB12C	4		T
N11	PB12D	4		C
U13	PB12E	4		T
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
V14	PB12F	4		C
T13	PB13A	4		T
P12	PB13B	4		C
R13	PB13C	4		T
N12	PB13D	4		C
V15	PB14A	4		T
U14	PB14B	4		C
V16	PB14C	4		T
GND	GND	-		
T14	PB14D	4		C
U15	PB15A	4		T
V17	PB15B	4		C
P13**	SLEEPN	-	SLEEPN	
T15	PB15D	4		
U16	PB16A	4		T
V18	PB16B	4		C
N13	PB16C	4		T
R14	PB16D	4		C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the [Thermal Management](#) document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following:

- [Thermal Management](#) document
- TN1090 - [Power Estimation and Management for MachXO Devices](#)
- Power Calculator tool included with the Lattice ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Conventional Packaging

Industrial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256C-3T100I	256	1.8V/2.5V/3.3V	78	-3	TQFP	100	IND
LCMxo256C-4T100I	256	1.8V/2.5V/3.3V	78	-4	TQFP	100	IND
LCMxo256C-3M100I	256	1.8V/2.5V/3.3V	78	-3	csBGA	100	IND
LCMxo256C-4M100I	256	1.8V/2.5V/3.3V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640C-3T100I	640	1.8V/2.5V/3.3V	74	-3	TQFP	100	IND
LCMxo640C-4T100I	640	1.8V/2.5V/3.3V	74	-4	TQFP	100	IND
LCMxo640C-3M100I	640	1.8V/2.5V/3.3V	74	-3	csBGA	100	IND
LCMxo640C-4M100I	640	1.8V/2.5V/3.3V	74	-4	csBGA	100	IND
LCMxo640C-3T144I	640	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo640C-4T144I	640	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo640C-3M132I	640	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo640C-4M132I	640	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo640C-3B256I	640	1.8V/2.5V/3.3V	159	-3	caBGA	256	IND
LCMxo640C-4B256I	640	1.8V/2.5V/3.3V	159	-4	caBGA	256	IND
LCMxo640C-3FT256I	640	1.8V/2.5V/3.3V	159	-3	ftBGA	256	IND
LCMxo640C-4FT256I	640	1.8V/2.5V/3.3V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200C-3T100I	1200	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMxo1200C-4T100I	1200	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMxo1200C-3T144I	1200	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo1200C-4T144I	1200	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo1200C-3M132I	1200	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo1200C-4M132I	1200	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo1200C-3B256I	1200	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMxo1200C-4B256I	1200	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMxo1200C-3FT256I	1200	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMxo1200C-4FT256I	1200	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280C-3T100I	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMxo2280C-4T100I	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMxo2280C-3T144I	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo2280C-4T144I	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo2280C-3M132I	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo2280C-4M132I	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo2280C-3B256I	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMxo2280C-4B256I	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMxo2280C-3FT256I	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMxo2280C-4FT256I	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND
LCMxo2280C-3FT324I	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	IND
LCMxo2280C-4FT324I	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	IND



MachXO Family Data Sheet

Revision History

June 2013

Data Sheet DS1002

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
		DC and Switching Characteristics	Security section updated.
			Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timingupdated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
		Pinout Information	JTAG Port Timing Specification updated (rev. A 0.16).
			SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
		Ordering Information	Logic Signal Connection section has been updated to include all devices/packages.
			Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/ LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.

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